

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC050N03LS G	**Issued**	11. April 2021
MA#	MA001823646		
Package	PG-TDSON-8-14	**Weight***	118.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.213	1.02	1.02	10194	10194
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82	
	non noble metal	zinc	7440-66-6	0.039	0.03		327	
	non noble metal	iron	7439-89-6	0.778	0.65		6541	
	non noble metal	copper	7440-50-8	31.590	26.56	27.25	265587	272537
wire	non noble metal	copper	7440-50-8	0.058	0.05	0.05	484	484
encapsulation	organic material	carbon black	1333-86-4	0.239	0.20		2011	
	plastics	epoxy resin	-	7.414	6.23		62334	
	inorganic material	silicondioxide	60676-86-0	40.181	33.80	40.23	337811	402156
leadfinish	non noble metal	tin	7440-31-5	1.243	1.04	1.04	10447	10447
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	315	315
solder	non noble metal	tin	7440-31-5	0.028	0.02		237	
	noble metal	silver	7440-22-4	0.035	0.03		296	
	non noble metal	lead	7439-92-1	1.345	1.13	1.18	11310	11843
heatspreader	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	zinc	7440-66-6	0.021	0.02		180	
	non noble metal	iron	7439-89-6	0.428	0.36		3594	
	non noble metal	copper	7440-50-8	17.360	14.60	14.98	145950	149769
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	iron	7439-89-6	0.017	0.01		142	
	non noble metal	copper	7440-50-8	16.898	14.21	14.22	142070	142255
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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